## Errata

# MSP430FR2353 Microcontroller



### **ABSTRACT**

This document describes the known exceptions to the functional specifications (advisories).

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### 1 Functional Advisories

Advisories that affect the device's operation, function, or parametrics.

✓ The check mark indicates that the issue is present in the specified revision.

Errata Number	Rev B
CPU46	✓
CS13	✓
PMM32	✓
RTC15	✓
TB25	✓
USCI42	✓
USCI45	✓
USCI47	✓
USCI50	1

### 2 Preprogrammed Software Advisories

Advisories that affect factory-programmed software.

✓ The check mark indicates that the issue is present in the specified revision.

The device does not have any errata for this category.

## 3 Debug Only Advisories

Advisories that affect only debug operation.

✓ The check mark indicates that the issue is present in the specified revision.

Errata Number	Rev B
EEM23	✓

### 4 Fixed by Compiler Advisories

Advisories that are resolved by compiler workaround. Refer to each advisory for the IDE and compiler versions with a workaround.

✓ The check mark indicates that the issue is present in the specified revision.

Errata Number	Rev B
CPU21	✓
CPU22	✓
CPU40	✓

Refer to the following MSP430 compiler documentation for more details about the CPU bugs workarounds.

### TI MSP430 Compiler Tools (Code Composer Studio IDE)

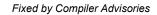
- MSP430 Optimizing C/C++ Compiler: Check the --silicon errata option
- MSP430 Assembly Language Tools

#### MSP430 GNU Compiler (MSP430-GCC)

- MSP430 GCC Options: Check -msilicon-errata= and -msilicon-errata-warn= options
- MSP430 GCC User's Guide

MSP430FR2353 Microcontroller

#### IAR Embedded Workbench





• IAR workarounds for msp430 hardware issues



## 5 Nomenclature, Package Symbolization, and Revision Identification

The revision of the device can be identified by the revision letter on the Package Markings or by the HW\_ID located inside the TLV structure of the device.

#### 5.1 Device Nomenclature

To designate the stages in the product development cycle, TI assigns prefixes to the part numbers of all MSP MCU devices. Each MSP MCU commercial family member has one of two prefixes: MSP or XMS. These prefixes represent evolutionary stages of product development from engineering prototypes (XMS) through fully qualified production devices (MSP).

XMS – Experimental device that is not necessarily representative of the final device's electrical specifications

MSP - Fully qualified production device

Support tool naming prefixes:

X: Development-support product that has not yet completed Texas Instruments internal qualification testing.

null: Fully-qualified development-support product.

XMS devices and X development-support tools are shipped against the following disclaimer:

"Developmental product is intended for internal evaluation purposes."

MSP devices have been characterized fully, and the quality and reliability of the device have been demonstrated fully. Tl's standard warranty applies.

Predictions show that prototype devices (XMS) have a greater failure rate than the standard production devices. TI recommends that these devices not be used in any production system because their expected end-use failure rate still is undefined. Only qualified production devices are to be used.

TI device nomenclature also includes a suffix with the device family name. This suffix indicates the temperature range, package type, and distribution format.

### 5.2 Package Markings

#### RSM32 QFN (RSM), 32 Pin 0 # = Die revision MSP430™ = Pin 1 location $\bigcirc$ **FRxxxx** = Lot trace code TI NNN# NNNN G4 RHA40 QFN (RHA), 40 Pin $\bigcirc$ # = Die revision MSP430™ = Pin 1 location $\bigcirc$ **FRxxxx** Ν = Lot trace code TI #NNN NNNN G4



#### **PT48**

### LQFP (TP), 48 Pin



# = Die revision
O = Pin 1 location
N = Lot trace code

#### DBT38

## TSSOP (DBT), 38 Pin



# = Die revision
O = Pin 1 location
N = Lot trace code

### **5.3 Memory-Mapped Hardware Revision (TLV Structure)**

Die Revision	TLV Hardware Revision
Rev B	20h

Further guidance on how to locate the TLV structure and read out the HW\_ID can be found in the device User's Guide.

## **6 Advisory Descriptions**

CPU21 CPU Module

Category Compiler-Fixed

**Function** Using POPM instruction on Status register may result in device hang up

**Description** When an active interrupt service request is pending and the POPM instruction is used to

set the Status Register (SR) and initiate entry into a low power mode, the device may

hang up.

**Workaround** None. It is recommended not to use POPM instruction on the Status Register.

Refer to the table below for compiler-specific fix implementation information.

IDE/Compiler	Version Number	Notes
IAR Embedded Workbench	Not affected	
TI MSP430 Compiler Tools (Code Composer Studio)	v4.0.x or later	User is required to add the compiler or assembler flag option below silicon_errata=CPU21
MSP430 GNU Compiler (MSP430-GCC)	MSP430-GCC 4.9 build 167 or later	

CPU22 CPU Module

Category Compiler-Fixed

**Function** Indirect addressing mode with the Program Counter as the source register may produce

unexpected results

**Description** When using the indirect addressing mode in an instruction with the Program Counter (PC)

as the source operand, the instruction that follows immediately does not get executed.

For example in the code below, the ADD instruction does not get executed.

mov @PC, R7 add #1h, R4

Workaround

Refer to the table below for compiler-specific fix implementation information.

IDE/Compiler	Version Number	Notes
IAR Embedded Workbench	Not affected	
TI MSP430 Compiler Tools (Code Composer Studio)	v4.0.x or later	User is required to add the compiler or assembler flag option below silicon_errata=CPU22
MSP430 GNU Compiler (MSP430-GCC)	MSP430-GCC 4.9 build 167 or later	

CPU40 CPU Module

Category Compiler-Fixed

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#### CPU40

#### CPU Module

#### **Function**

PC is corrupted when executing jump/conditional jump instruction that is followed by instruction with PC as destination register or a data section

#### Description

If the value at the memory location immediately following a jump/conditional jump instruction is 0X40h or 0X50h (where X = don't care), which could either be an instruction opcode (for instructions like RRCM, RRAM, RLAM, RRUM) with PC as destination register or a data section (const data in flash memory or data variable in RAM), then the PC value is auto-incremented by 2 after the jump instruction is executed; therefore, branching to a wrong address location in code and leading to wrong program execution.

For example, a conditional jump instruction followed by data section (0140h).

@0x8012 Loop DEC.W R6

@0x8014 DEC.W R7

@0x8016 JNZ Loop

@0x8018 Value1 DW 0140h

#### Workaround

In assembly, insert a NOP between the jump/conditional jump instruction and program code with instruction that contains PC as destination register or the data section.

Refer to the table below for compiler-specific fix implementation information.

IDE/Compiler	Version Number	Notes
IAR Embedded Workbench	IAR EW430 v5.51 or later	For the command line version add the following information Compiler:hw_workaround=CPU40 Assembler:-v1
TI MSP430 Compiler Tools (Code Composer Studio)	v4.0.x or later	User is required to add the compiler or assembler flag option below silicon_errata=CPU40
MSP430 GNU Compiler (MSP430-GCC)	Not affected	

#### CPU46 CPU Module

Category

**Functional** 

**Function** 

POPM peforms unexpected memory access and can cause VMAIFG to be set

Description

When the POPM assembly instruction is executed, the last Stack Pointer increment is followed by an unintended read access to the memory. If this read access is performed on vacant memory, the VMAIFG will be set and can trigger the corresponding interrupt (SFRIE1.VMAIE) if it is enabled. This issue occurs if the POPM assembly instruction is performed up to the top of the STACK.

#### Workaround

If the user is utilizing C, they will not be impacted by this issue. All TI/IAR/GCC pre-built libraries are not impacted by this bug. To ensure that POPM is never executed up to the memory border of the STACK when using assembly it is recommended to either

- 1. Initialize the SP to
- a. TOP of STACK 4 bytes if POPM.A is used
- b. TOP of STACK 2 bytes if POPM.W is used



### CPU46

#### CPU Module

OR

2. Use the POPM instruction for all but the last restore operation. For the last restore operation use the POP assembly instruction instead.

For instance, instead of using:

POPM.W #5,R13

#### Use:

POPM.W #4,R12 POP.W R13

Refer to the table below for compiler-specific fix implementation information.

IDE/Compiler	Version Number	Notes
IAR Embedded Workbench	Not affected	C code is not impacted by this bug. User using POPM instruction in assembler is required to implement the above workaround manually.
TI MSP430 Compiler Tools (Code Composer Studio)	Not affected	C code is not impacted by this bug. User using POPM instruction in assembler is required to implement the above workaround manually.
MSP430 GNU Compiler (MSP430-GCC)	Not affected	C code is not impacted by this bug. User using POPM instruction in assembler is required to implement the above workaround manually.

#### CS13 CS Module

Category

**Functional** 

**Function** 

Device may enter lockup state during transition from AM to LPM3/4 if DCO frequency is above 2 MHz.

**Description** 

The device might enter lockup state if DCO frequency is above 2 MHz and two events happen at the same time:

- 1) The device transitions from AM to LPM3/4 (e.g. during ISR exits or Status Register modifications)
- 2) An interrupt is requested (e.g. GPIO interrupt).

This condition can be recovered by BOR/Power cycle.



### CS13 (continued)

#### CS Module

#### Workaround

1. Use DCOCLK at 2MHz or lower.

OR

2. Use LPM0/x.5 instead of LPM3/4.

OR

3. Use external high-frequency crystal if it is available on the device.

OR

4. Set DCOCLK to 2MHz or lower before entering LPM3/4, then restore DCOCLK after wake-up. Note using peripherals using clocks derived from DCOCLK might be affected during this interval.

#### EEM23

#### **EEM Module**

#### Category

#### Debug

### **Function**

EEM triggers incorrectly when modules using wait states are enable; Incorrect operation when more than two software breakpoints are set in the continual instruction addresses

### Description

When modules using wait states (USB, MPY, CRC and FRAM controller in manual mode) are enabled, the EEM may trigger incorrectly. This can lead to an incorrect profile counter value or cause issues with the EEMs data watch point, state storage, and breakpoint functionality.

When more than 2 software breakpoints are set in continuous instruction addresses (for example, more than 2 NOP instructions, the address is increased 2 bytes between these 2 instructions), program counter (PC) will stuck at the first breakpoint and can't move on.

#### Workaround

None.

Note

This erratum affects debug mode only.

### **PMM32**

### PMM Module

### Category

Functional

#### **Function**

Device may enter lockup state or execute unintentional code during transition from AM to LPM3/4

### Description

The device might enter lockup state or start executing unintentional code resulting in unpredictable behavior depending on the contents of the address location- if any of the two conditions below occurs:

#### Condition1:

The following three events happen at the same time:

1) The device transitions from AM to LPM3/4 (e.g. during ISR exits or Status Register modifications),

AND

### PMM32 (continued)

#### **PMM Module**

2) An interrupt is requested (e.g. GPIO interrupt),

AND

3) MODCLK is requested (e.g. triggered by ADC) or removed (e.g. end of ADC conversion).

Modules which can trigger MODCLK clock requests/removals are ADC, eUSCI and CapTIvate (if exist).

If clock events are started by the CPU (e.g. eUSCI during SPI master transmission), they can not occur at the same time as the power mode transition and thus should not be affected. The device should only be affected when the clock event is asynchronous to the power mode transition.

The device can recover from this lockup condition by a PUC/BOR/Power cycle (e.g. enable Watchdog to trigger PUC).

#### Condition2:

The following events happen at the same time:

1) The device transitions from AM to LPM3/4 (e.g. during ISR exits or Status Register modifications),

AND

2) An interrupt is requested (e.g. GPIO interrupt),

**AND** 

3) Neither MODCLK nor SMCLK are running (e.g. requested by a peripheral),

**AND** 

4) SMCLK is configured with a different frequency than MCLK.

The device can recover from this lockup condition by a BOR/Power cycle.

#### Workaround

1. Use LPM0/1/x.5 instead of LPM3/4.

OR

2. Place the FRAM in INACTIVE mode before any entry to LPM3/4 by clearing the FRPWR bit and FRLPMPWR bit (if exist) in the GCCTL0 register. This must be performed from RAM as shown below:

```
// define a function in RAM #pragma CODE_SECTION(enterLpModeFromRAM,".TI.ramfunc") void enterLpModeFromRAM(unsigned short lowPowerMode); 
//call this function before any entry to LPM3/4 void enterLpModeFromRAM(unsigned short lowPowerMode) {
```

Advisory Descriptions

### PMM32 (continued) PMM Module

FRCTL0 = FRCTLPW; GCCTL0 &= ~(FRPWR+FRLPMPWR); //clear FRPWR and FRLPMPWR FRCTL0 H = 0; //re-lock FRCTL bis SR register(lowPowerMode);

#### RTC15 RTC Module

### Category

**Functional** 

#### **Function**

RTC Counter stops operating if RTC Counter clock source is changed from XT1CLK to another source while XT1CLK is stopped

### **Description**

If XT1CLK is used as the clock source for the RTC Counter and XT1CLK stops (e.g. oscillator fault), if the RTC Counter clock source is changed by user software (e.g. in the clock fault handling ISR) from XT1CLK to a different clock source while XT1CLK is stopped the RTC Counter hangs. In this hang state, the RTC Counter stops operating and cannot be restarted without a device reset via the hardware RST pin, a power-cycle of the device, or recovery of XT1CLK oscillation.

#### Workaround

To change the RTC Counter clock source due to an oscillator fault, in the ISR for handling the OFIFG fault, use this software sequence:

- 1) Change the RTC Counter clock source away from XT1CLK normally
- 2) Reconfigure the XIN pin as a GPIO output, then toggle the GPIO twice with at least 2 rising or falling edges.

At this point the RTC Counter will be able to resume operation.

#### **TB25**

#### TB Module

#### Category

Functional

#### **Function**

In up mode, TBxCCRn value is immediately transferred to TBxCLn when TBxCCTLn.CLLD bits are set or 0x01 or 0x10

#### **Description**

IF Timer B is configured for Up mode,

the compare latch load event (TBxCCTLn.CLLD bits) setting is configured to update

TBxCCRn when TBxR reaches 0,

**THEN** 

TBxCCRn will update immediately instead of the described condition.

This is contrary to the user guide description of TBxCCTLn.CLLD = 0x01 or 0x10 modes.

#### Workaround

If user needs to update TBxCCRn value when TBxR counts to 0 in Timer B up mode:

- 1. Set TBxCCTLn. CLLD = 0x00
- 2. Enable the Timer B interrupt (TBIE) in TBxCTL
- 3. Update TBxCCRn value within interrupt routine.

Timer B Interrupt would need to be serviced in a timely manner to mitigate disruption or unintended timer output if an output mode is used.



USCI42 USCI Module

Category Functional

Function UART asserts UCTXCPTIFG after each byte in multi-byte transmission

**Description** UCTXCPTIFG flag is triggered at the last stop bit of every UART byte transmission,

independently of an empty buffer, when transmitting multiple byte seguences via UART.

The erroneous UART behavior occurs with and without DMA transfer.

Workaround None.

USCI45 USCI Module

**Category** Functional

Function Unexpected SPI clock stretching possible when UCxCLK is asynchronous to MCLK

**Description** In rare cases, during SPI communication, the clock high phase of the first data bit may

be stretched significantly. The SPI operation completes as expected with no data loss. This issue only occurs when the USCI SPI module clock (UCxCLK) is ACLK and it is

asynchronous to the system clock (MCLK).

Workaround Ensure that the USCI SPI module clock (UCxCLK) and the CPU clock (MCLK) are

synchronous to each other.

USCI47 USCI Module

**Category** Functional

**Function** eUSCI SPI slave with clock phase UCCKPH = 1

**Description** The eUSCI SPI operates incorrectly under the following conditions:

1. The eUSCI A or eUSCI B module is configured as a SPI slave with clock phase mode

UCCKPH = 1

AND

2. The SPI clock pin is not at the appropriate idle level (low for UCCKPL = 0, high for

UCCKPL = 1) when the UCSWRST bit in the UCxxCTLW0 register is cleared.

If both of the above conditions are satisfied, then the following will occur:

eUSCI\_A: the SPI will not be able to receive a byte (UCAxRXBUF will not be filled and UCRXIFG will not be set) and SPI slave output data will be wrong (first bit will be missed and data will be shifted).

eUSCI\_B: the SPI receives data correctly but the SPI slave output data will be wrong (first

byte will be duplicated or replaced by second byte).

**Workaround** Use clock phase mode UCCKPH = 0 for MSP SPI slave if allowed by the application.

OR

The SPI master must set the clock pin at the appropriate idle level (low for UCCKPL = 0,

high for UCCKPL = 1) before SPI slave is reset (UCSWRST bit is cleared).

OR

For eUSCI A: to detect communication failure condition where UCRXIFG is not set, check



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**USCI47** (continued) **USCI Module** 

both UCRXIFG and UCTXIFG. If UCTXIFG is set twice but UCRXIFG is not set, reset the MSP SPI slave by setting and then clearing the UCSWRST bit, and inform the SPI master

to resend the data.

USCI50 USCI Module

**Category** Functional

**Function** Data may not be transmitted correctly from the eUSCI when operating in SPI 4-pin master

mode with UCSTEM = 0

**Description** When the eUSCI is used in SPI 4-pin master mode with UCSTEM = 0 (STE pin used as

an input to prevent conflicts with other SPI masters), data that is moved into UCxTXBUF while the UCxSTE input is in the inactive state may not be transmitted correctly. If the eUSCI is used with UCSTEM = 1 (STE pin used to output an enable signal), data is

transmitted correctly.

Workaround When using the STE pin in conflict prevention mode (UCSTEM = 0), only move data

into UCxTXBUF when UCxSTE is in the active state. If an active transfer is aborted by UCxSTE transitioning to the master-inactive state, the data must be rewritten into UCxTXBUF to be transferred when UCxSTE transitions back to the master-active state.

**INSTRUMENTS** Revision History www.ti.com

**7 Revision History**NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from July 14, 2021 to August 27, 2021		Page
•	TB25 was added to the errata documentation	6
•	TB25 Description was updated	1 <mark>1</mark>
	TB25 Workaround was updated	
	·	

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